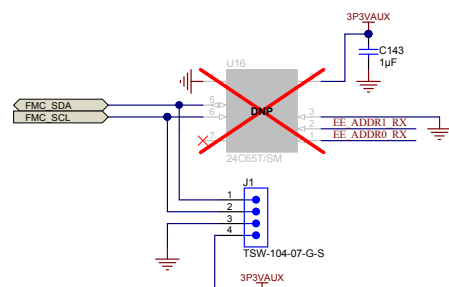
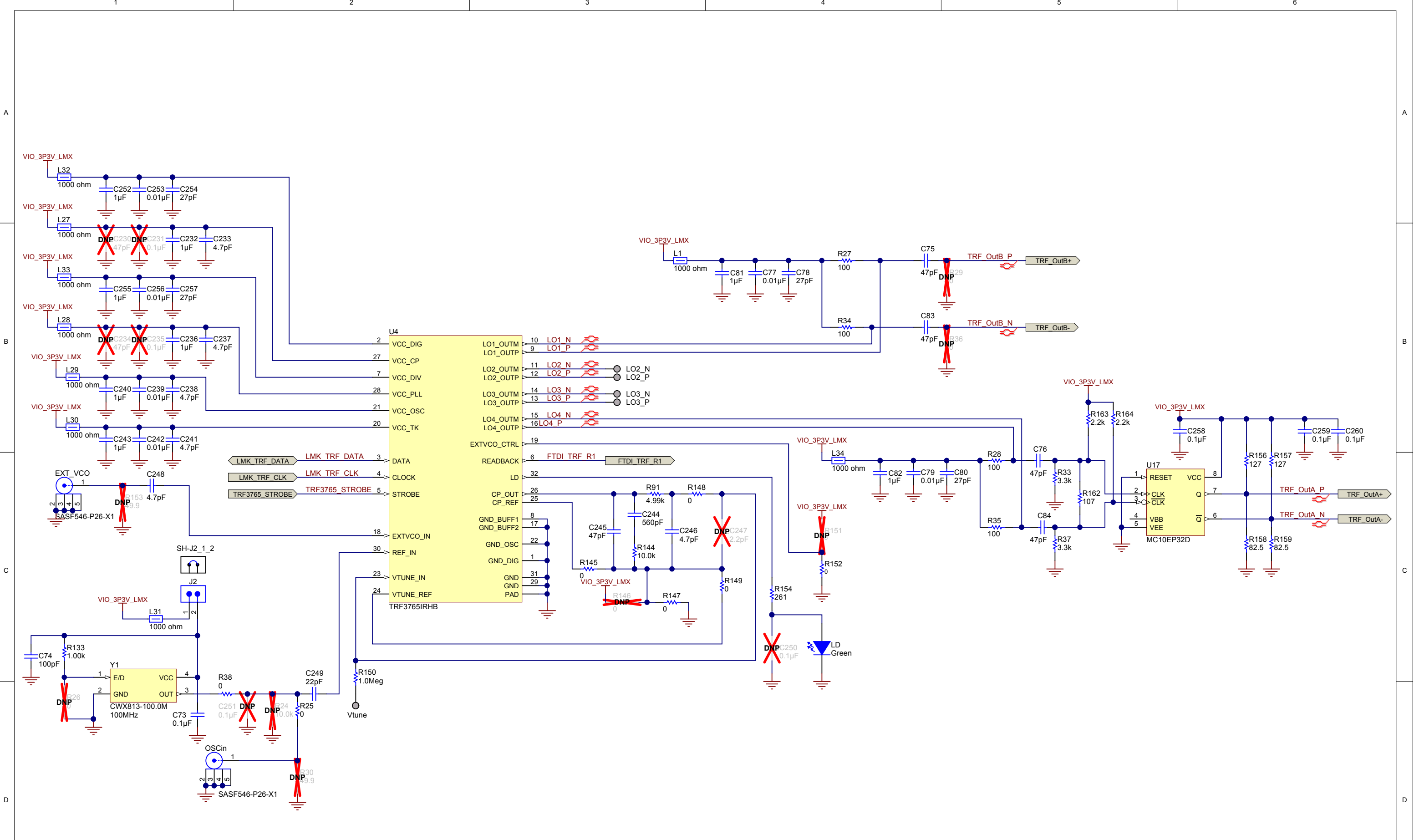


The D<7,0> connections polarity have been swapped from the TI standard FMC ADC guidelines to ease routing. This is accounted for in the FPGA code.



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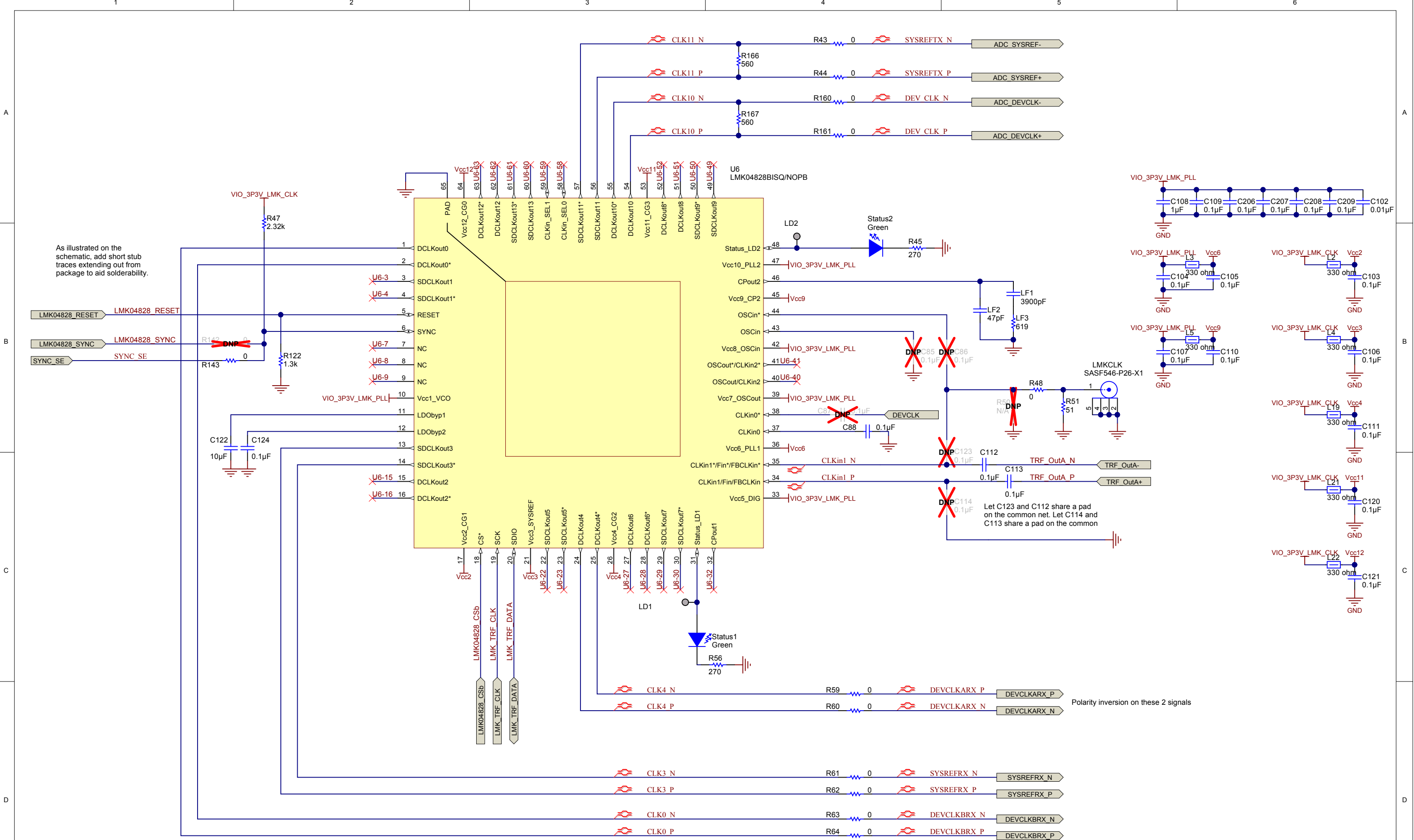


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Designed for: Internal Use Only		Mod. Date: 9/10/2014	
Project Title: ADC12JXXXXEVM		Number: 600847	
Sheet Title: TRF3765		Rev: A	
Assembly Variant: 002_ADC12J4000EVM		Sheet: 3 of 7	
File: ADC12JXXXXEVM_A_3_TRF3765.SchDoc		Size: B	
Engineer: Jim Brinkhurst		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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As illustrated on the schematic, add short stub traces extending out from package to aid solderability.

Let C123 and C112 share a pad on the common net. Let C114 and C113 share a pad on the common

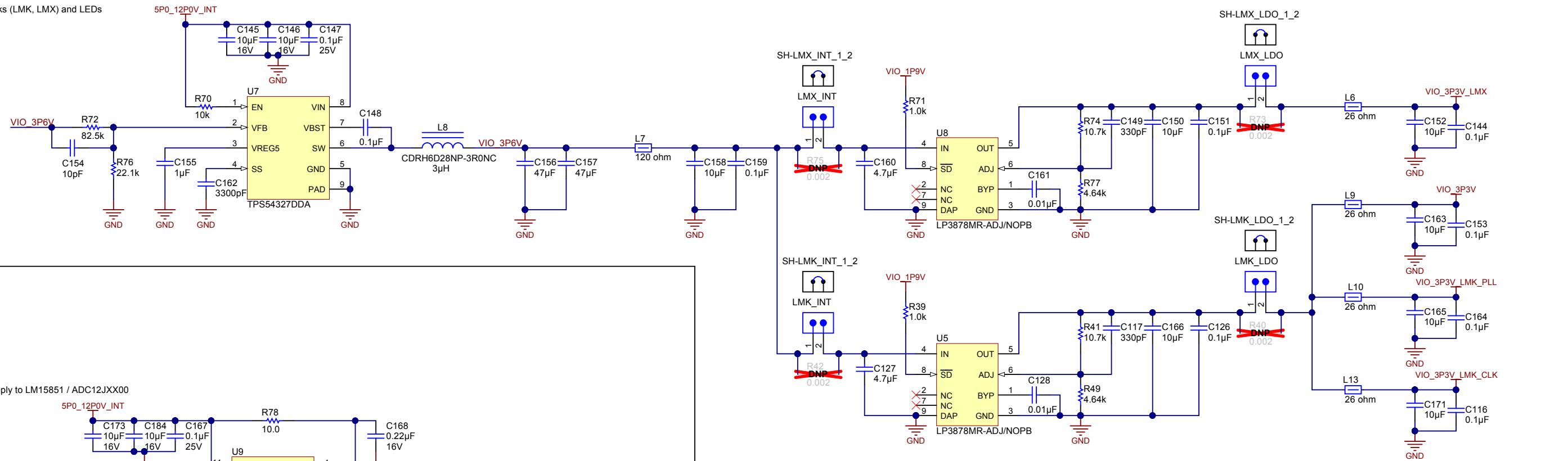
Polarity inversion on these 2 signals

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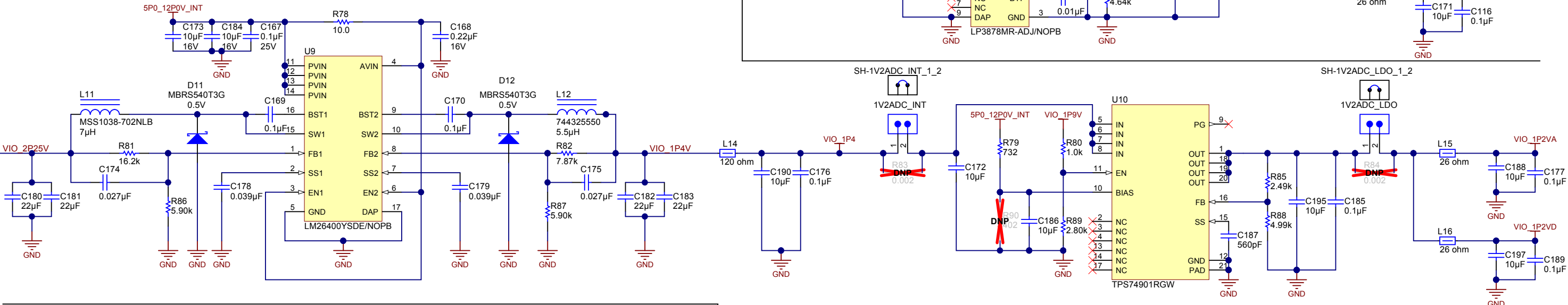
Number: 600847	Rev: A	Designed for: Internal Use Only	Mod. Date: 9/29/2014
SVN Rev: Unknown revision		Project Title: ADC12JXXXXEVM	
Drawn By:		Sheet Title:	
Engineer: Jim Brinkhurst		Assembly Variant: 002_ADC12J4000EVM	Sheet: 4 of 7
		File: ADC12JXXXXEVM_A_4_LMK04828.SchDoc	Size: B
		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	<a href="http://www.ti.com">http://www.ti.com</a>
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3.3V supply to clocks (LMK, LMX) and LEDs

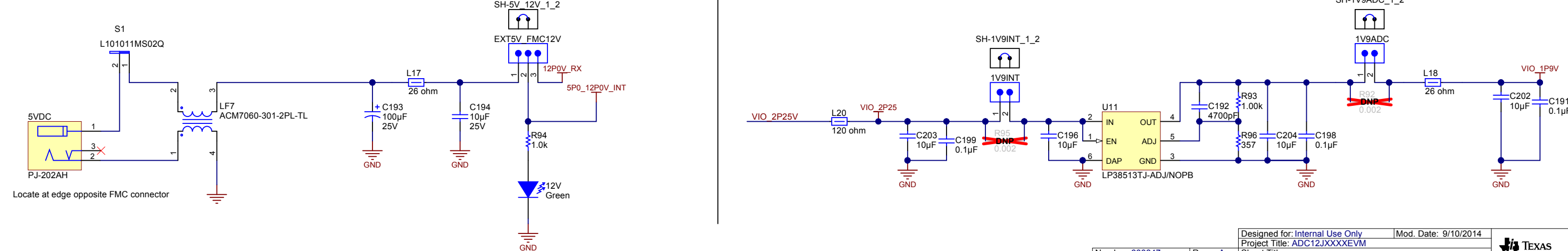


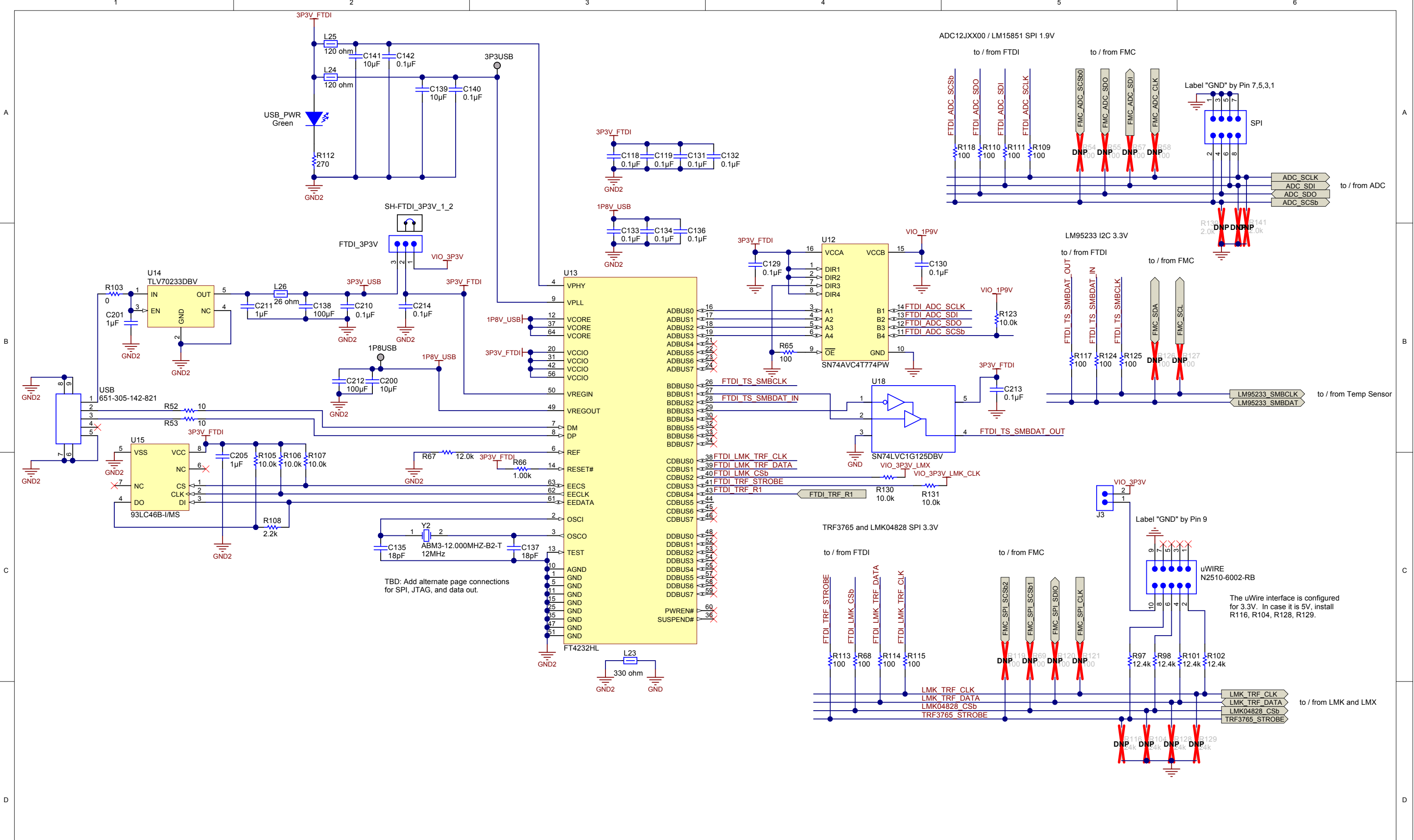
1.9V and 1.2V supply to LM15851 / ADC12JXX00



12V main supply, from jack or via FMC connector to regulators

Add text label: "5V VIA JACK" and "12V VIA FMC, Install R90 for 12V operation"





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A

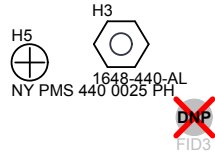
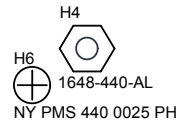
A

~~DNP~~  
FID1

PCB Number: 600847  
PCB Rev: A

PCB  
ESD LOGO  
ESD Susceptible

PCB  
LOGO  
Texas Instruments



~~DNP~~  
FID2

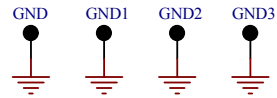
~~DNP~~  
FID3

H9  
**MECH**  
FMC - FMC Screw  
PMSSS 256 0075 PH

H10  
**MECH**  
FMC - FMC Nut

H11  
**MECH**  
FMC - FMC Screw  
PMSSS 256 0075 PH

H12  
**MECH**  
FMC - FMC Nut



Place at least two of the GND test points in the power section.

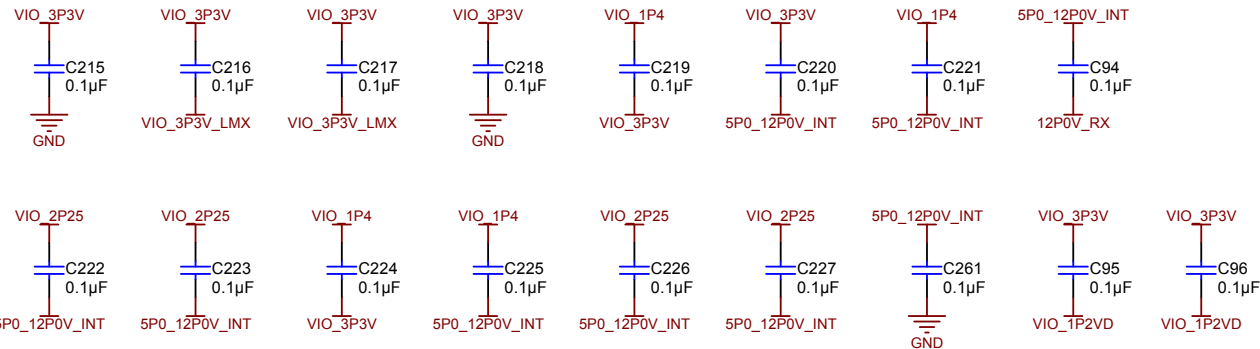
LBL1  
PCB Label  
Size: 0.65" x 0.20 "

ZZ1  
**Label Assembly Note**  
This Assembly Note is for PCB labels only

ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



B

B

C

C

D

D

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Number: 600847	Rev: A	Mod. Date: 9/10/2014
SVN Rev: Unknown revision		Project Title: ADC12JXXXXEVM
Drawn By:	Assembly Variant: 002_ADC12J4000EVM	Sheet: 7 of 7
Engineer: Jim Brinkhurst	File: ADC12JXXXXEVM_A_7_Hardware.SchDoc	Size: B
Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



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